

Feature:

- Antireflective Pb free silver paste
- High resistance member of the system Ag 3902 / Ag 3903

Benefits:

- Wide window of compatibility with several black enamels
- Superior substrate wetting
- High chemical durability

PROCESSING CONDITIONS

Printing: 200 – 250 mesh screen and 0.4 mm minimum line width are recommended.

Soldering: 47% Sn, 40% Pb, 10% Bi, 3% Ag solder at 230°C.

Shelf life: 8 months @ 4°-10°C, 6 months @ 10-24°C

Thinners: Thinning is not recommended, the paste is optimized to the correct viscosity for screen printing. Use the Chimet 0202 IT/0201IT to replace solvent losses, by contacting the local Chimet technician

TYPICAL PROPERTIES

Metal content:

Ag **65.0 %**

Resistivity:

32 mΩ · μm

Viscosity:

40 – 60 Pa.s

STANDARD TEST CONDITIONS

Viscosity test:

Viscosimeter Brookfield DV II, Cylinder Ø = 4 cm h = 7 cm, Spindle 7 R at 10 r.p.m. and 23.5 (± 0,5)°C.

Resistance test:

Circuit: 1000 x 1 mm

Printing : 250 mesh

Fired thickness: Taylor-Hobson profilometer

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